

LP6872P100

# Packaged 0.5W Power PHEMT

# **FEATURES**

- +27 dBm Typical Power at 15 GHz
- 11 dB Typical Power Gain at 15 GHz
- Low Intermodulation Distortion
- 50% Power-Added-Efficiency
- Color-coded by I<sub>DSS</sub> range



#### **DESCRIPTION AND APPLICATIONS**

The LP6872P100 is a packaged Aluminum Gallium Arsenide / Indium Gallium Arsenide (AlGaAs/InGaAs) Pseudomorphic High Electron Mobility Transistor (PHEMT), utilizing an Electron-Beam direct-write 0.25  $\mu$ m by 720  $\mu$ m Schottky barrier gate. The recessed "mushroom" gate structure minimizes parasitic gate-source and gate resistances. The epitaxial structure and processing have been optimized for reliable high-power applications. The LP6872 also features Si<sub>3</sub>N<sub>4</sub> passivation and is available in die form.

Typical applications include commercial and military high-performance power amplifiers, including SATCOM uplink transmitters, and medium-haul digital radio transmitters. Space level screening to FSS JANS grade is also available.

The LP6872-P100 may be procured in a variety of grades, depending upon specific user requirements. Standard lot screening is patterned after MIL-STD-19500, JANC grade.

SYMBOLS	PARAMETERS		MIN	ΤΥΡ	MAX	UNITS
I <sub>DSS</sub>	Saturated Drain-Source Current	LP6872-P100-1 BLUE	180	195	206	mA
	$V_{DS} = 2V V_{GS} = 0V$	LP6872-P100-2 GREEN	207	220	233	
		LP6872-P100-3 RED	234	245	260	
P <sub>1dB</sub>	Output Power at 1dB Gain Compression					
	$V_{DS} = 8.0V, I_{DS} = 50\% I_{DSS}$	<i>f</i> = 15 GHz	25.5	27.0		dBm
G <sub>1dB</sub>	Power Gain at 1dB Gain Compress	sion				
	$V_{DS} = 8.0V, I_{DS} = 50\% I_{DSS}$	<i>f</i> = 15 GHz	8.0	9.5		dB
$\eta_{ADD}$	Power-Added Efficiency			50		%
I <sub>MAX</sub>	Maximum Drain-Source Current	$V_{DS} = 2V V_{GS} = +1V$		385		mA
G <sub>M</sub>	Transconductance	$V_{DS} = 2V V_{GS} = 0V$	170	220		mS
VP	Pinch-Off Voltage	$V_{DS} = 2V I_{DS} = 4mA$	-0.25	-1.2	-2.0	V
I <sub>GSO</sub>	Gate-Source Leakage Current	$V_{GS} = -5V$		10	50	μA
BV <sub>GS</sub>	Gate-Source Breakdown Voltage	I <sub>GS</sub> = 4mA	-12	-15		V
$BV_{GD}$	Gate-Drain Breakdown Voltage	$I_{GD} = 4mA$	-12	-16		V

# PERFORMANCE SPECIFICATIONS ( $T_A = 25^{\circ}C$ )

# **Get Package Model**

**DSS-033 WF** 

# Packaged 0.5W Power PHEMT

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#### PACKAGE OUTLINE: (DIMENSIONS IN INCHES)



# Get Package Model

#### **DSS-033 WF**

REC	OMMENDED CONTINU	OUS	
OPERATING LIMITS			
SYMBOL	PARAMETER	<b>RATING<sup>2</sup></b>	
V <sub>DS</sub>	Drain-Source Voltage	8V	
$V_{GS}$	Gate-Source Voltage	-1V	
I <sub>DS</sub>	Drain-Source Current	$0.8 \times I_{DSS}$	
l <sub>G</sub>	Gate Current	8 mA	
P <sub>IN</sub>	RF Input Power	150 mW	
Т <sub>СН</sub>	Channel Temperature	150°C	
T <sub>STG</sub>	Storage Temperature	-20/50°C	
PT	Power Dissipation	1.4 W <sup>3,4</sup>	
G <sub>XdB</sub>	Gain Compression	8 dB	

# **Filtronic** Solid State

ABSOLUTE MAXIMUM RATINGS					
(25°C)					
SYMBOL	PARAMETER	<b>RATING<sup>1</sup></b>			
V <sub>DS</sub>	Drain-Source Voltage	12V			
$V_{GS}$	Gate-Source Voltage	-4V			
I <sub>DS</sub>	Drain-Source Current	2 x I <sub>DSS</sub>			
l <sub>G</sub>	Gate Current	30 mA			
P <sub>IN</sub>	RF Input Power	300 mW			
Т <sub>СН</sub>	Channel Temperature	175°C			
T <sub>STG</sub>	Storage Temperature	-65/175°C			
PT	Power Dissipation	1.7W <sup>3,4</sup>			

# NOTES:

- 1. Operating conditions that exceed the Absolute Maximum Ratings could result in permanent damage to the device.
- 2. Recommended Continuous Operating Limits should be observed for reliable device operation.
- 3. Power Dissipation defined as:  $P_T \equiv (P_{DC} + P_{IN}) P_{OUT}$ , where:  $P_{DC} = DC$  bias power,  $P_{OUT} = RF$  output power, and  $P_{IN} = RF$  input power.
- 4. Power Dissipation to be de-rated as follows above 25°C:
  - Absolute Maximum:  $P_T = 1.7W - (11mW/^{\circ}C) \times T_{HS}$
  - Recommended Continuous Operating: P<sub>T</sub> = 1.4W (11mW/°C) x T<sub>HS</sub>
  - where  $T_{HS}$  = heatsink or ambient temperature.

5. Specifications subject to change without notice.

#### HANDLING PRECAUTIONS:

Care should be exercised during handling to avoid damage to the devices. Proper Electrostatic Discharge (ESD) precautions should be observed at all stages of storage, handling, assembly, and testing. These devices should be treated as Class 1A (0-500V), and further information on ESD control measures can be found in MIL-STD-1686 and MIL-HDBK-263.

#### **APPLICATIONS NOTES AND DESIGN DATA:**

Applications Notes are available from your local FSS Sales Representative, or directly from the factory. Complete design data, including S-parameters, Noise data, and Large-Signal models, is available on 3.5" diskette, or may be down-loaded Web Page.